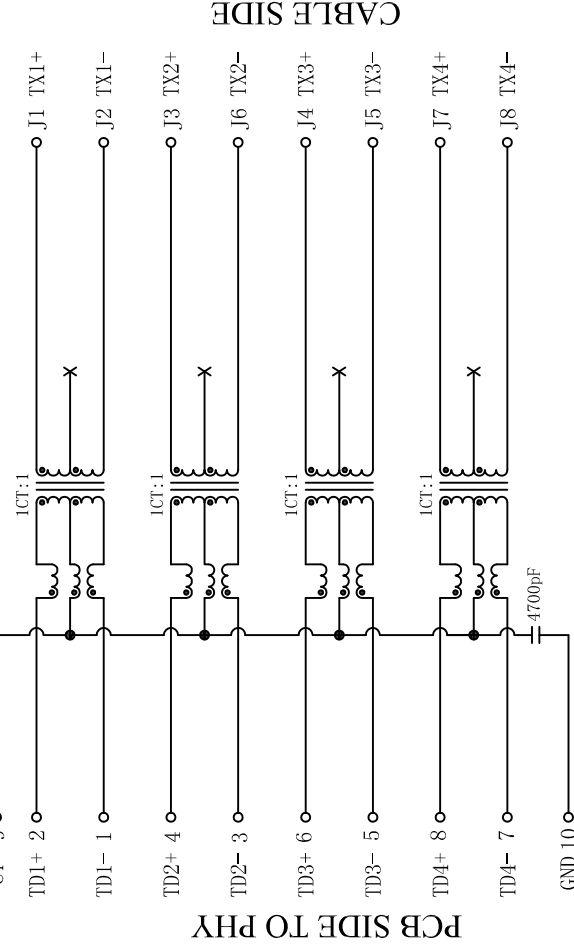
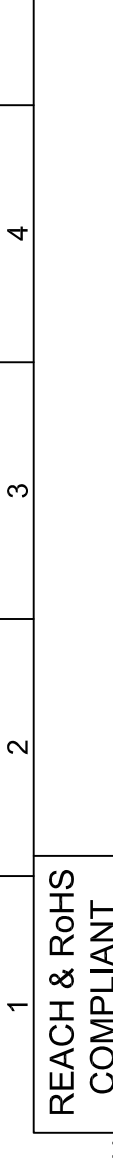


REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	TW.Xu	2018.11.02

REACH & RoHS COMPLIANT



Electrical:

- Turn ratio: 2~1: J1~J2=1CT:1CT(±2%).
4~3: J3~J6=1CT:1CT(±2%).
6~5: J4~J5=1CT:1CT(±2%).
8~7: J7~J8=1CT:1CT(±2%).
- OCL: 350uH Min. at 100KHz 100mV 8mA DC.
- Insertion Loss: -1.0 dB Max 1~100MHz.
- Return loss: -20dB Min 1~10MHz;
-16dB Min 10~30MHz;
-12dB Min 30~60MHz;
-10dB Min 60~80MHz;
- Cross talk: -40dB Min 1~30MHz;
-35dB Min 30~60MHz;
-30dB Min 60~100MHz;
- CMR: -35dB Min 1~100MHz;
- Hi-Pot: 1500V AC & 2250V DC
6S 1mA PRI TO SEC

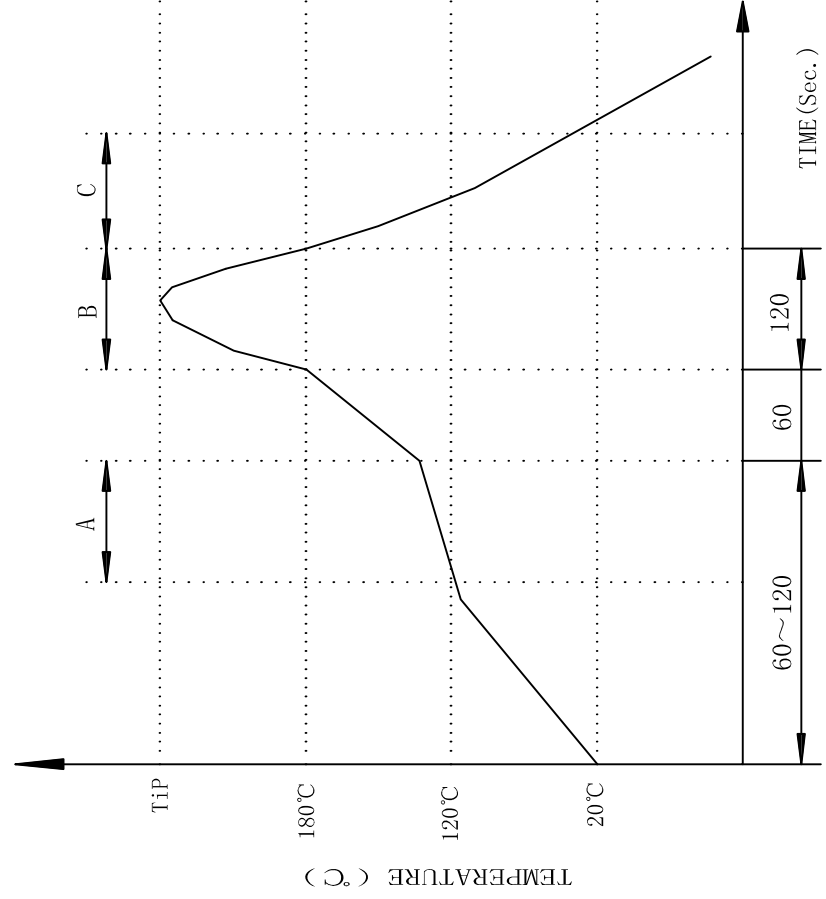
TITLE: TAB-UP 1X4 1000BASE		SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED	APPROVED BY: JP.Gong
PART NO.: FC-2513NL		SACLE 1:1	REV A0	x±0.35 .x±0.30	CHECKED BY: TW.Xu
REMARK:		SHEET 2/3		.xx°±0.25 .xxx°±1.0°	DESIGNED BY: TW.Xu

东莞市浚程电子科技有限公司
DONG GUAN FU CHENG ELECTRONIC TECHNOLOGY Co., LTD

REACH & RoHS COMPLIANT

PROFILE OF WAVE SOLDER

REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	TW.Xu	2018.11.02



A. Preheating
 B. Soldering
 C. Gradual Cooling
 Tip temperature: $260 \pm 5^\circ\text{C}$.
 Tip temperature time: 5Sec Max.
 Tip melting point of Sn96.5/Ag3/Cu0.5: 217°C .

Remarks: after wave soldering, the plastic positioning columns of the product which under the PCB will be slightly melted, but it won't affect its function.

TITLE: TAB-UP 1X4 1000BASE		UNITS MM(INCH)	GENERAL TOLERANCES UNLESS SPECIFIED	APPROVED BY: JP.Gong
SIZE A4	REV A0	x \pm 0.35 .x \pm 0.30	x $^\circ$ \pm 3.0 $^\circ$.x $^\circ$ \pm 2.0 $^\circ$	CHECKED BY: TW.Xu
SACLE 1:1		.xx \pm 0.25 .xxx \pm 0.10	.xx $^\circ$ \pm 1.5 $^\circ$.xxx $^\circ$ \pm 1.0 $^\circ$	DESIGN BY: TW.Xu
SHEET 3/3				

东莞市浚程电子科技有限公司
 DONG GUAN FU CHENG ELECTRONIC TECHNOLOGY Co., LTD